

Catalog # 44-6200 Bis(cyclopentadienyl)ruthenium, 99% (99.9%-Ru) (Ruthenocene)



Ru



## Thermal Behavior:

- Melting point: 194-198°C [1]
- Sublimation: 120°C/high vacuum [1]
- Vapor pressure: 0.16 Torr/84°C, 0.29 Torr/91°C, 0.50 Torr/97°C [2-3]

## Technical Notes:

1. ALD/CVD precursor for ruthenium thin film and nanocomposites deposition

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.
Ru	ALD	45-70°C	7.5 Torr	O <sub>2</sub>	275-400°C	4-5
	ALD	85°C	-	O <sub>2</sub>	300°C	6
	CVD	95-115°C	40 mTorr	O <sub>2</sub>	225-500°C	7
	PELAD	85°C	-	<sup>PL</sup> O <sub>2</sub> or <sup>Therm</sup> NH <sub>3</sub>	300°C	8
Pt:Ru	ALD	80°C	7.5 mTorr	MeCpPtMe <sub>3</sub> , O <sub>2</sub>	245°C	9
	PEALD	-	-	MeCpPtMe <sub>3</sub> , <sup>PL</sup> O <sub>2</sub>	300°C	10
Ru <sub>2</sub> O	LPCVD	90°C	4.5 Torr	O <sub>2</sub>	400°C	11

## References:

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